

Features

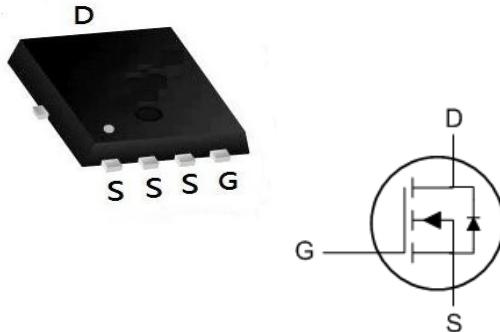
- Split Gate Trench MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low $R_{DS(ON)}$

Product Summary

| BVDSS | RDS(on) | ID |
|-------|---------|------|
| 100V | 4.5mΩ | 100A |

Applications

- DC-DC Converters
- Power management functions
- Synchronous-rectification applications

PDFN5060-8L Pin Configuration**Absolute Maximum Ratings ($T_c = 25^\circ\text{C}$, unless otherwise noted)**

| Parameter | | Symbol | Value | Unit |
|--|-------------------------|----------------|------------|------|
| Drain-Source Voltage | | V_{DS} | 100 | V |
| Gate-Source Voltage | | V_{GS} | ± 20 | V |
| Continuous Drain Current | $T_c=25^\circ\text{C}$ | I_D | 100 | A |
| | $T_c=100^\circ\text{C}$ | | 60 | |
| Pulsed Drain Current ⁴ | | I_{DM} | 380 | A |
| Single Pulse Avalanche Energy ³ | | E_{AS} | 205 | mJ |
| Total Power Dissipation | $T_c=25^\circ\text{C}$ | P_D | 113.6 | W |
| Operating Junction and Storage Temperature Range | | T_J, T_{STG} | -55 to 150 | °C |

Thermal Characteristics

| Parameter | Symbol | Value | Unit |
|--|-----------------|-------|------|
| Thermal Resistance from Junction-to-Ambient ¹ | $R_{\theta JA}$ | 58 | °C/W |
| Thermal Resistance from Junction-to-Case | $R_{\theta JC}$ | 1.1 | °C/W |

N-Ch100V Fast Switching MOSFETs

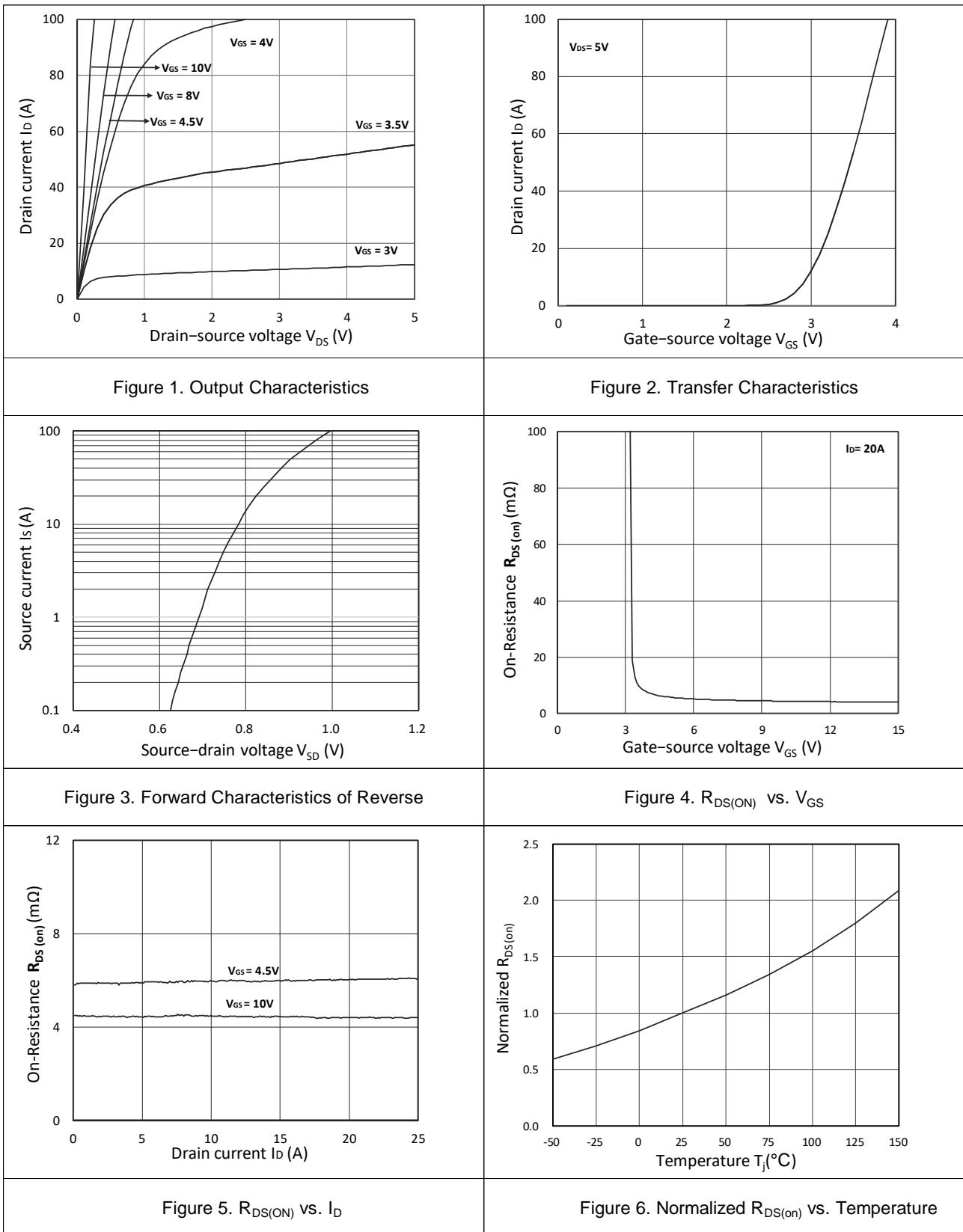
Electrical Characteristics ($T_J = 25^\circ\text{C}$, unless otherwise noted)

| Parameter | Symbol | Test Conditions | Min. | Typ. | Max. | Unit |
|---|-----------------------------|---|------|------|-----------|------------------|
| Static Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | $V_{(\text{BR})\text{DSS}}$ | $V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$ | 100 | - | - | V |
| Gate-body Leakage current | I_{GSS} | $V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = \pm 20\text{V}$ | - | - | ± 100 | nA |
| Zero Gate Voltage Drain Current $T_J=25^\circ\text{C}$ | I_{DSS} | $V_{\text{DS}} = 100\text{V}, V_{\text{GS}} = 0\text{V}$ | - | - | 1 | μA |
| $T_J=100^\circ\text{C}$ | | | - | - | 100 | |
| Gate-Threshold Voltage | $V_{\text{GS}(\text{th})}$ | $V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$ | 1.2 | 1.8 | 2.5 | V |
| Drain-Source on-Resistance ² | $R_{\text{DS}(\text{on})}$ | $V_{\text{GS}} = 10\text{V}, I_D = 20\text{A}$ | - | 4.5 | 6 | $\text{m}\Omega$ |
| | | $V_{\text{GS}} = 4.5\text{V}, I_D = 15\text{A}$ | - | 6.6 | 9 | |
| Dynamic Characteristics | | | | | | |
| Input Capacitance | C_{iss} | $V_{\text{DS}} = 50\text{V}, V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$ | - | 4400 | - | pF |
| Output Capacitance | C_{oss} | | - | 645 | - | |
| Reverse Transfer Capacitance | C_{rss} | | - | 20 | - | |
| Switching Characteristics | | | | | | |
| Gate Resistance | R_g | $V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 0\text{V}, f = 1\text{MHz}$ | - | 1.7 | - | Ω |
| Total Gate Charge | Q_g | $V_{\text{GS}} = 10\text{V}, V_{\text{DS}} = 50\text{V}, I_D = 20\text{A}$ | - | 75 | - | nC |
| Gate-Source Charge | Q_{gs} | | - | 17 | - | |
| Gate-Drain Charge | Q_{gd} | | - | 13 | - | |
| Turn-on Delay Time | $t_{\text{d}(\text{on})}$ | $V_{\text{GS}} = 10\text{V}, V_{\text{DS}} = 50\text{V}, R_G = 3\Omega, I_D = 20\text{A}$ | - | 15.4 | - | ns |
| Rise Time | t_r | | - | 13 | - | |
| Turn-off Delay Time | $t_{\text{d}(\text{off})}$ | | - | 34 | - | |
| Fall Time | t_f | | - | 6.2 | - | |
| Drain-Source Body Diode Characteristics | | | | | | |
| Diode Forward Voltage ² | V_{SD} | $I_F = 20\text{A}, V_{\text{GS}} = 0\text{V}$ | - | - | 1.2 | V |
| Continuous Source Current ^{1,5} | I_s | $V_G = V_D = 0\text{V}$, Force Current | - | - | 95 | A |
| Body Diode Reverse Recovery Time | t_{rr} | $I_F = 20\text{A}, dI/dt = 100\text{A}/\mu\text{s}$ | - | 55 | - | ns |
| Body Diode Reverse Recovery Charge | Q_{rr} | | - | 101 | - | nC |

Notes:

1. Repetitive rating, pulse width limited by junction temperature $T_{J(\text{MAX})} = 150^\circ\text{C}$.
2. The EAS data shows Max. rating . The test condition is $V_{\text{DD}} = 25\text{V}, V_{\text{GS}} = 10\text{V}, L = 0.4\text{mH}, I_{\text{AS}} = 40\text{A}$
3. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper,The value in any given application depends on the user's specific board design.
4. The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
5. This value is guaranteed by design hence it is not included in the production test..

Typical Characteristics



N-Ch100V Fast Switching MOSFETs

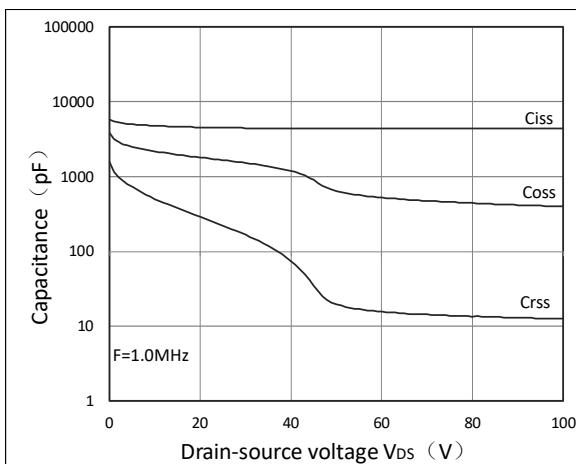


Figure 7. Capacitance Characteristics

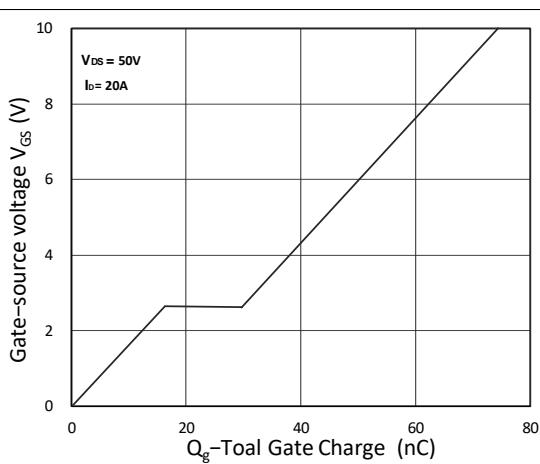


Figure 8. Gate Charge Characteristics

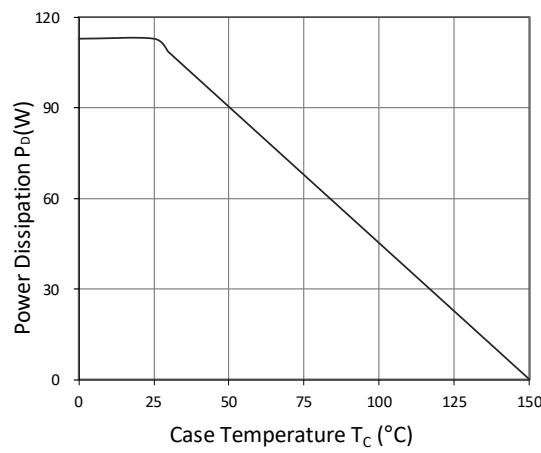


Figure 9. Power Dissipation

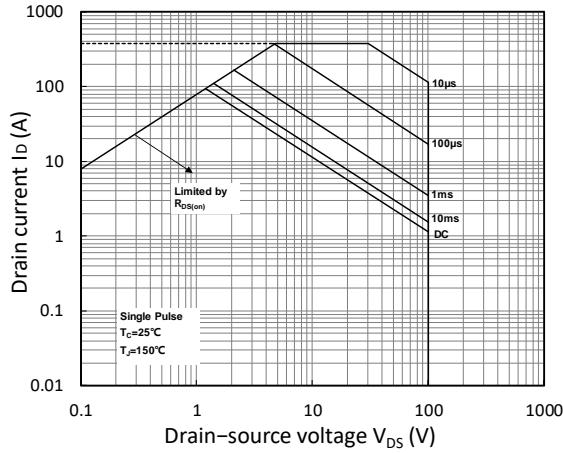


Figure 10. Safe Operating Area

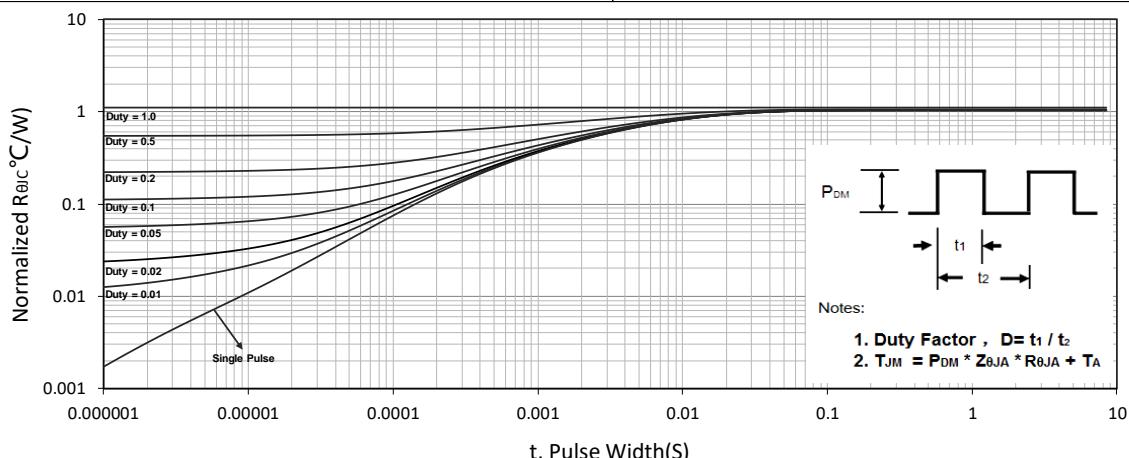


Figure 11. Normalized Maximum Transient Thermal Impedance

■ Test circuits and waveforms

N-Ch100V Fast Switching MOSFETs

Test Circuit

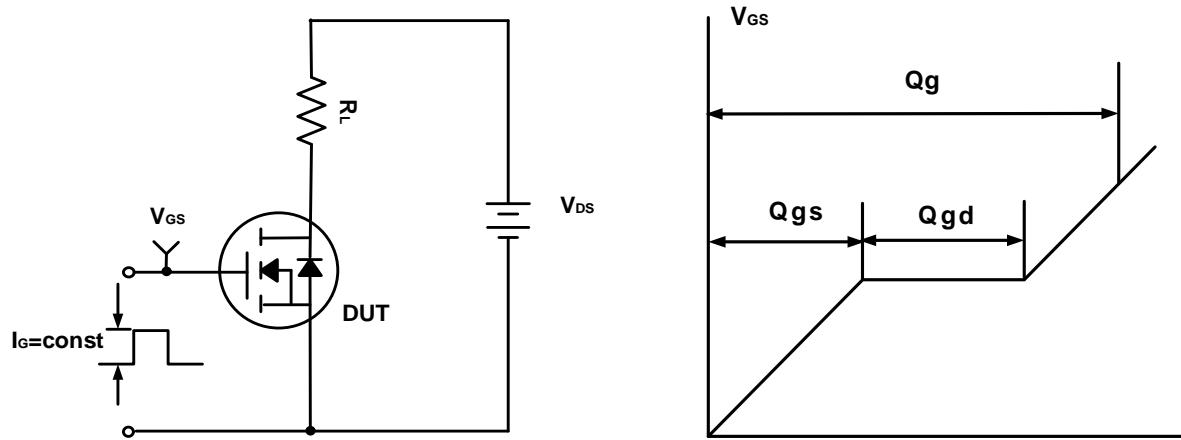


Figure A. Gate Charge Test Circuit & Waveforms

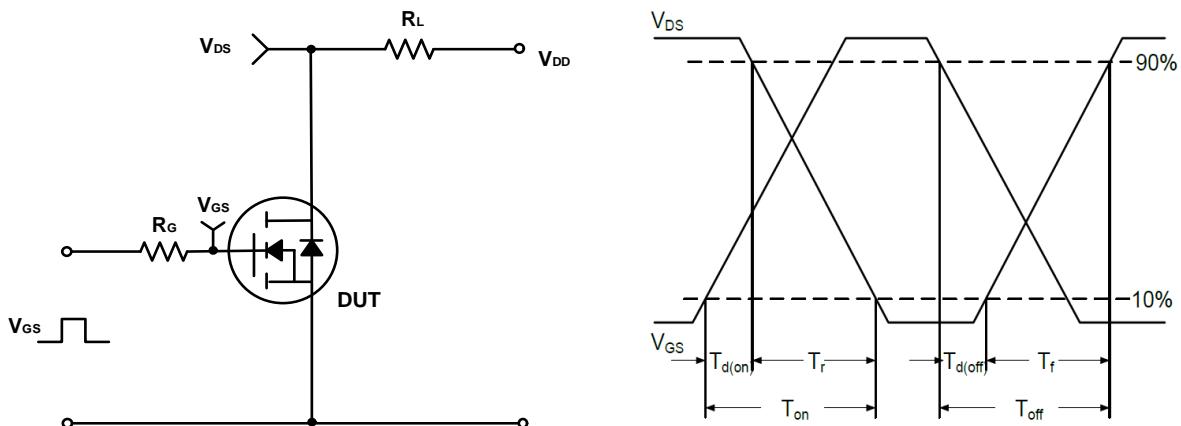


Figure B. Switching Test Circuit & Waveforms

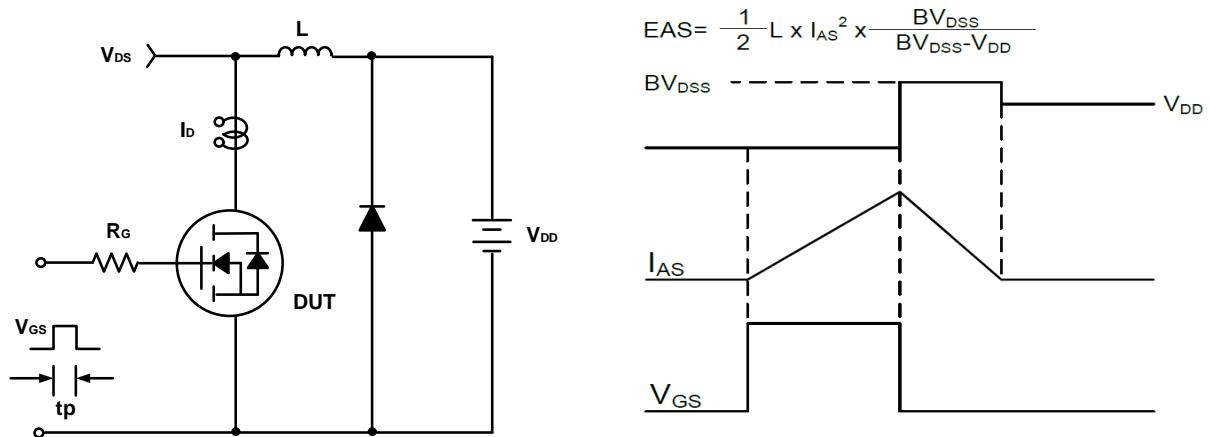
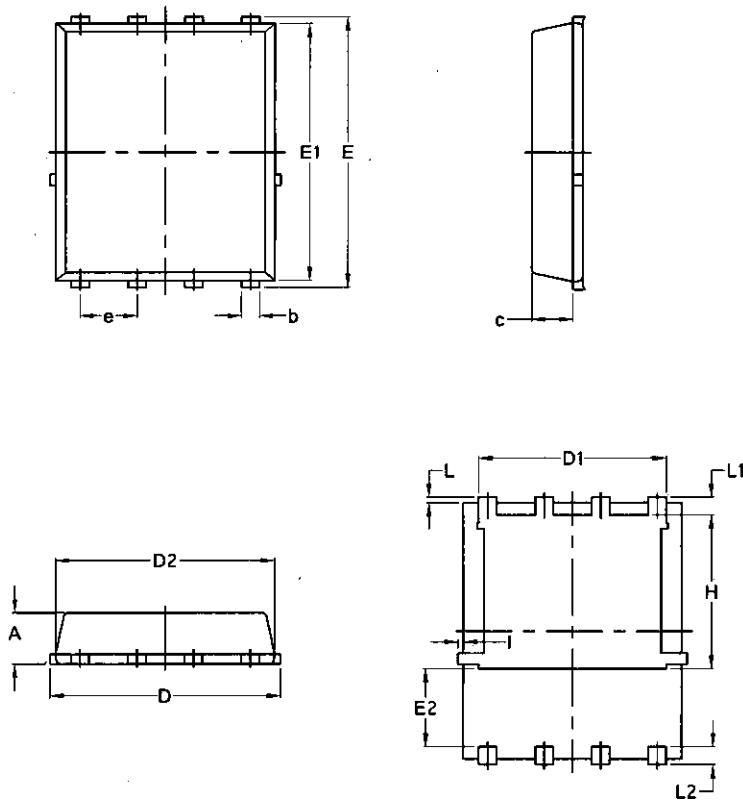


Figure C. Unclamped Inductive Switching Circuit & Waveforms

Package Mechanical Data-PDFN5060-8L-Single



| Symbol | Common | | | |
|--------|----------|--------|----------|--------|
| | mm | | Inch | |
| | Mim | Max | Min | Max |
| A | 1.03 | 1.17 | 0.0406 | 0.0461 |
| b | 0.34 | 0.48 | 0.0134 | 0.0189 |
| c | 0.824 | 0.0970 | 0.0324 | 0.082 |
| D | 4.80 | 5.40 | 0.1890 | 0.2126 |
| D1 | 4.11 | 4.31 | 0.1618 | 0.1697 |
| D2 | 4.80 | 5.00 | 0.1890 | 0.1969 |
| E | 5.95 | 6.15 | 0.2343 | 0.2421 |
| E1 | 5.65 | 5.85 | 0.2224 | 0.2303 |
| E2 | 1.60 | / | 0.0630 | / |
| e | 1.27 BSC | | 0.05 BSC | |
| L | 0.05 | 0.25 | 0.0020 | 0.0098 |
| L1 | 0.38 | 0.50 | 0.0150 | 0.0197 |
| L2 | 0.38 | 0.50 | 0.0150 | 0.0197 |
| H | 3.30 | 3.50 | 0.1299 | 0.1378 |
| I | / | 0.18 | / | 0.0070 |